

ADCLK925BCPZ

Data Sheet

SiGe ECL Clock/Data Buffers

Manufacturers <u>Analog Devices, Inc</u>

Package/Case LFCSP16

Product Type Integrated Circuits (ICs)

RoHS

Lifecycle



Images are for reference only

Please submit RFQ for ADCLK925BCPZ or Email to us: sales@ovaga.com We will contact you in 12 hours.

RFO

General Description

ADCLK925BCPZ is a high-speed clock buffer designed by Analog Devices, a leading semiconductor manufacturer. Here are some details about this IC:

Features

Provides 1:2 differential clock outputs

Operating frequency range: DC to 7 GHz

Low additive jitter: 47 fs rms

Low output-to-output skew: 3 ps

Input clock signal can be single-ended or differential

Supports a wide range of input voltage levels (from 0.4V to 2.0V)

Low power consumption: 170 mW at 2.5 GHz

Application

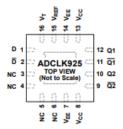
High-speed data communication systems

Test and measurement equipment

Data acquisition systems

Instrumentation and control systems

Medical imaging equipment



NOTES

1. NC = NO CONNECT. DO NOT CONNECT TO THIS PIN.

2. EXPOSED PAD. THE EXPOSED PAD IS NOT ELECTRICALLY CONNECTED TO ANY PART OF THE CIRCUIT.

IT CAN BE LEFT FLOATING FOR OPTIMAL ELECTRICAL ISOLATION BETWEEN THE PACKAGE HANDLE
AND THE SUBSTRATE OF THE DIE. IT CAN ALSO BE SOLDERED TO THE APPLICATION BOARD IF IMPROVED
THERMAL ANDION RECHANICAL STABILITY IS DESIRED. EXPOSED METAL AT THE CORNERS OF THE PACKAGE
IS CONNECTED TO THIS EXPOSED PAD. ALLOW SUFFICIENT CLEARANCE TO VIAS AND OTHER COMPONENTS.

Figure 6. ADCLK925 Pin Configuration

Table 6. Pin Function Descriptions for 1:2 ADCLK925 Buffer

Pin No.	Mnemonic	Description
1	D	Noninverting Input.
2	D	Inverting Input.
3, 4, 5, 6	NC	No Connect. No physical connection to the die.
7, 14	V _{EE}	Negative Supply Voltage.
8, 13	V _{cc}	Positive Supply Voltage.
9	Q2	Inverting Output 2.
10	Q2	Noninverting Output 2.
11	Q1	Inverting Output 1.
12	Q1	Noninverting Output 1.
15	V _{REF}	Reference Voltage. Reference voltage for biasing ac-coupled inputs.
16	V _T	Center Tap. Center tap of 100Ω input resistor.
	EPAD	Exposed Pad. The exposed pad is not electrically connected to any part of the circuit. It can be left floating for optimal electrical isolation between the package handle and the substrate of the die. It can also be soldered to the application board if improved thermal and/or mechanical stability is desired. Exposed metal at the corners of the package is connected to this exposed pad. Allow sufficient clearance to vias and other components.

Related Products



ADUM1300

Analog Devices, Inc



ADG5409BCPZ

Analog Devices, Inc

LFCSP-16



ADR391AUJZ

Analog Devices, Inc

SOT23-5



ADM7171ACPZ

Analog Devices, Inc

LFCSP8



ADL5310ACPZ

Analog Devices, Inc

LFCSP-24



ADG3308BCPZ

Analog Devices, Inc

20LFCS



ADCMP600BKSZ

Analog Devices, Inc

SC-70-5



ADCMP601BKSZ

Analog Devices, Inc

SC70